

On page 11, lines 8-15, please delete the existing paragraph and replace it with the following paragraph:

BR
Since the process gases injected from the first and second gas pipes 110a and 110b are randomly distributed over a substrate 114, over the susceptor 112, and around the inner sidewalls of the processing chamber 100, the process efficiency of the process gases is lowered. Thus, the ring-shaped third gas pipe 110c is required around the susceptor 112 in order to increase the efficiency of the process gases that participate in a plasma process. Moreover, a lower RF power supply 116 is connected to the susceptor 112 and supplies a high frequency power having a frequency of 2 to 4 MHz. So a plasma dry cleaning process can be performed in inner surfaces of the processing chamber 100.

IN THE CLAIMS

Please amend claim 12 to read as follows:

BR
C
12. (Amended) The apparatus according to claim 7, wherein at least one gas pipe surrounds the means for fixing the substrate in a shape of a ring and the end of the [this] gas pipe bends toward and over the means for fixing the substrate so as to inject the process gases upward.

REMARKS

In the Office Action mailed on October 3, 2002, the Examiner required affirmation of the provisional election of Species B (claims 7-12), required correction of various informalities in the specification and in claim 12, objected to the drawings for failing to include the reference number 116, rejected claims 7-8 and 10-12 under 35 USC 103(a) as being unpatentable over Schneider et al., EP 0838841 A2 in view of Singh et al., U.S. Patent No. 6,042,687, Qian et al., U.S. Patent No. 6,447,636 B1, Stimson, U.S. Patent No. 6,345,588 B1, and Collins et al. U.S. Patent No. 5,556,501, and rejected claim 9 under 35 USC 103(a) as being unpatentable over Schneider et al., '841 in view of Singh et al. '687, Qian et al. '636, Stimson '588, and Collins et al. '501 as applied to claims 7-8 and 10-12 and further in view of Hama et al., U.S. Patent No. 5,525,159.